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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor Shozo Nagano et al.
Assignee Honeywell International, Inc.
Group Art Unit Unknown
Examiner Unknown
Attorney's Docket No. 30-5000-(4015)-Div1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, Metal Alloys for Use as a Conductive Interconnection in an Integrated Circuit, and Physical Vapor Deposition Targets

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. Copies of the cited prior art references are attached. No admission is made regarding whether all the submitted references are prior art.

This Information Disclosure Statement is being filed within three months of the filing date of the application or before the mailing of a first Office Action, whichever occurs last. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925. Please credit Deposit Account No. 23-0925 with any overpayment of the above fee.

Citation of these references is respectfully requested.

Respectfully submitted,

Date: 4-4-01

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